

Smart High-Side Power Switch

Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown with restart
- Overvoltage protection (including load dump)
- Fast demagnetization of inductive loads
- Reverse battery protection with external resistor
- Open drain diagnostic output for overtemperature and short circuit
- Open load detection in OFF State with external resistor
- CMOS compatible input
- Loss of GND and loss of $V_{\rm bb}$ protection
- ESD Protection
- Very low standby current
- Green product (RoHS-compliant)

Application

- All types of resistive, inductive and capacitive loads
- \bullet μC compatible power switch for 12 V, 24 V and 42 V DC applications
- Replaces electromechanical relays and discrete circuits

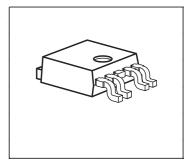
General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, monolithically integrated in Smart SIPMOS[®] technology. Providing embedded protective functions.

Product Summary

Overvoltage protection	V _{bb(AZ)}	62	V
Operating voltage	V _{bb(on)}	652	V
On-state resistance	R _{ON}	200	mΩ
Nominal load current	I _{L(ISO)}	1.8	A

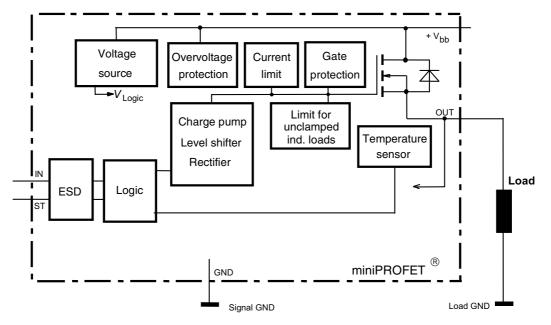




PG-TO252-5-11

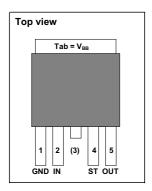


Block Diagram



Pin	Symbol	Function
1	GND	Logic ground
2	IN	Input, activates the power switch in case of logic high signal
3	Vbb	Positive power supply voltage
4	ST	Diagnostic feedback
5	OUT	Output to the load
TAB	Vbb	Positive power supply voltage

Pin configuration





Maximum Ratings at $T_j = 25^{\circ}$ C, unless otherwise specifie

Parameter	Symbol	Value	Unit
Supply voltage	V _{bb}	52	V
Supply voltage for full short circuit protection	V _{bb(SC)}	50	
Continuous input voltage	V _{IN}	-10 +16	
Load current (Short - circuit current, see page 5)	IL	self limited	A
Current through input pin (DC)	I _{IN}	± 5	mA
Operating temperature	Tj	-40+150	°C
Storage temperature	T _{stg}	-55 +150	
Power dissipation ¹⁾	P _{tot}	41.6	W
Inductive load switch-off energy dissipation ¹⁾²⁾	E _{AS}	150	mJ
single pulse, (see page 9)			
Tj =150 °C, <i>I</i> _L = 1 A			
Load dump protection ²⁾ $V_{\text{LoadDump}}^{3} = V_{\text{A}} + V_{\text{S}}$	VLoaddump		V
$R_{\rm I}$ =2 Ω , $t_{\rm d}$ =400ms, $V_{\rm IN}$ = low or high, $V_{\rm A}$ =13.5V			
R _L = 13.5 Ω		73.5	
$R_{\rm L}$ = 27 Ω		88.5	
Electrostatic discharge voltage (Human Body Model)	V _{ESD}		kV
according to ANSI EOS/ESD - S5.1 - 1993			
ESD STM5.1 - 1998			
Input pin		± 1	
all other pins		± 5	

Thermal Characteristics

junction - case:	R _{thJC}	-	-	3	K/W
Thermal resistance @ min. footprint	R _{th(JA)}	-	80	-	K/W
Thermal resistance @ 6 cm ² cooling area ¹⁾	R _{th(JA)}	-	45	60	

¹Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6 cm2 (one layer, 70µm thick) copper area for drain connection. PCB is vertical without blown air.

2not subject to production test, specified by design

 $^{3}V_{\text{Loaddump}}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839 .

Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND pin, e.g. with a

 150Ω resistor in GND connection. A resistor for the protection of the input is integrated.



Electrical Characteristics

Parameter and Conditions	Symbol		Values		Unit
_at T_j = -40+150°C, V_{bb} = 1242V, unless otherwise specified		min.	typ.	max.	
Load Switching Capabilities and Characterist	ics				
On-state resistance	R _{ON}				mΩ
$T_{\rm j}$ = 25 °C, $I_{\rm L}$ = 1 A, $V_{\rm bb}$ = 952 V		-	150	200	
<i>T</i> _j = 150 °C		-	270	380	
Nominal load current; Device on PCB ¹	I _{L(ISO)}	1.8	2.2	-	А
$T_{\rm C}$ = 85 °C, $V_{\rm ON}$ = 0.5 V					
Turn-on time to 90% V _{OUT}	t _{on}	-	80	180	μs
$R_{\rm L}$ = 47 Ω					
Turn-off time to 10% V _{OUT}	t _{off}	-	80	200	
$R_{\rm L}$ = 47 Ω					
Slew rate on 10 to 30% V _{OUT} ,	dV/dt _{on}	-	0.7	2	V/µs
$R_{\rm L} = 47 \ \Omega, \ V_{\rm bb} = 13.5 \ V$					
Slew rate off 70 to 40% V _{OUT} ,	-dV/dt _{off}	-	0.9	2	
$R_{\rm L}$ = 47 Ω , $V_{\rm bb}$ = 13.5 V					

Operating Parameters

Operating voltage	V _{bb(on)}	6	-	52	V
Undervoltage shutdown of charge pump	V _{bb(under)}				
<i>T</i> _j = -40+85 °C		-	-	4	
<i>T</i> _j = 150 °C		-	-	5.5	
Undervoltage restart of charge pump	V _{bb(u cp)}	-	4	5.5	
Standby current	I _{bb(off)}				μA
<i>T</i> _j = -40+85 °C, <i>V</i> _{IN} = low		-	-	15	
$T_{\rm j}$ = +150 °C ²), $V_{\rm IN}$ = low		-	-	18	
Leakage output current (included in <i>I</i> _{bb(off)})	I _{L(off)}	-	-	5	
$V_{\rm IN} = {\rm low}$					
Operating current	I _{GND}	-	0.8	2	mA
V _{IN} = high					

¹Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6 cm2 (one layer, 70µm thick) copper area for drain connection. PCB is vertical without blown air.

²higher current due temperature sensor



Electrical Characteristics

Parameter and Conditions	Symbol		Values	-	Unit
at T_i = -40+150°C, V_{bb} = 1242V, unless otherwise specified		min.	typ.	max.	
Protection Functions ¹⁾					
Initial peak short circuit current limit (pin 3 to 5)	I _{L(SCp)}				А
<i>T</i> _j = -40 °C, <i>V</i> _{bb} = 20 V, <i>t</i> _m = 150 μs		-	-	9	
<i>T</i> _j = 25 °C		-	6.5	-	
<i>T</i> _j = 150 °C		4	-	-	
T_j = -40+150 °C, V_{bb} > 40 V, (see page 12)		-	52)	-	
Repetitive short circuit current limit	I _{L(SCr)}				
T _j = T _{jt} (see timing diagrams)					
$V_{\rm bb}$ < 40V		-	6	-	
$V_{\rm bb} > 40V$		-	4.5	-	
Output clamp (inductive load switch off)	V _{ON(CL)}	59	63	-	V
at $V_{OUT} = V_{bb} - V_{ON(CL)}$,					
$I_{\rm bb} = 4 \mathrm{mA}$					
Overvoltage protection ³⁾	V _{bb(AZ)}	62	-	-	
l _{bb} = 4 mA					
Thermal overload trip temperature	T _{jt}	150	-	-	°C
Thermal hysteresis	ΔT_{jt}	-	10	-	К

Reverse Battery

Reverse battery ⁴⁾	-V _{bb}	-	-	52	V
Drain-source diode voltage ($V_{OUT} > V_{bb}$)	-V _{ON}	-	600	-	mV
<i>T</i> _j = 150 °C					

5

¹Integrated protection functions are designed to prevent IC destruction under fault conditions

described in the data sheet. Fault conditions are considered as "outside" normal operating range.

Protection functions are not designed for continuous repetitive operation .

 $^{^{2}\}mbox{not}$ subject to production test, specified by design

 $^{^3}$ see also V_{ON(CL)} in circuit diagram on page 8

⁴Requires a 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Power dissipation is higher compared to normal operating conditions due to the voltage drop across the drain-source diode. The temperature protection is not active during reverse current operation! Input current has to be limited (see max. ratings page 3).



Electrical Characteristics

Parameter and Conditions	Symbol	Values		alues U	
_at T_j = -40+150°C, V_{bb} = 1242V, unless otherwise specified		min.	typ.	max.	
Input and Status feedback					
Input turn-on threshold voltage	V _{IN(T+)}	-	-	2.2	V
Input turn-off threshold voltage	V _{IN(T-)}	0.8	-	-	
Input threshold hysteresis	$\Delta V_{\rm IN(T)}$	-	0.4	-	
Off state input current $V_{\rm IN} = 0.7 V$	/ _{IN(off)}	1	-	25	μA
On state input current $V_{\rm IN} = 5 \rm V$	I _{IN(on)}	3	-	25	
Status output (open drain), Zener limit voltage <i>I</i> _{ST} = 1.6 mA	V _{ST(high)}	5.4	6.1	-	V
Status output (open drain), ST low voltage	V _{ST(low)}				
<i>T</i> _j = -40+25 °C, <i>I</i> _{ST} = 1.6 mA		-	-	0.4	
Τ _j = 150 °C, <i>I</i> _{ST} = 1.6 mA		-	-	0.6	
Status invalid after positive input slope ¹) $V_{bb} = 20 V$	t _{d(ST+)}	-	120	160	μs
Status invalid after negative input slope ¹⁾	t _{d(ST-)}	-	250	400	1
Input resistance (see page 8)	$R_{\rm I}$	2	3.5	5	kΩ

Diagnostic Characteristics

Short circuit detection voltage	V _{OUT(SC)}	-	2.8	-	V
Open load detection voltage ²⁾	V _{OUT(OL)}	-	3	4	
Internal output pull down ³⁾	R _O	65	200	750	kΩ
(see page 9 and 14)					
$V_{OUT(OL)} = 4 V$					

¹no delay time after overtemperature switch off and short circuit in on-state

²External pull up resistor required for open load detection in off state.

³not subject to production test, specified by design



	Input	Output	Status
	level	level	
Normal	L	L	н
operation	Н	Н	Н
Short circuit	L	L	Н
to GND	Н	L *	L
Short circuit to	L	Н	L
V _{bb} (in off-state)	Н	Н	Н
Overload	L	L	Н
	Н	H **	Н
Overtemperature	L	L	Н
	Н	L	L
Open Load in	L	Z	H (L ¹⁾)
off-state	Н	Н	Н

*) Out ="L": *V*_{OUT} < 2.8V typ.

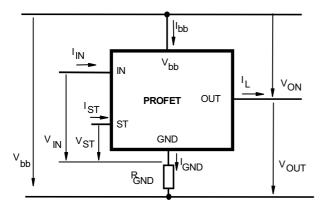
**) Out ="H": *V*_{OUT} > 2.8V typ.

Z = high impedance, potential depends on external circuit

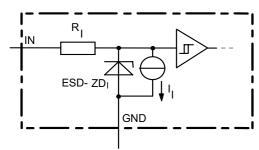
 $^{^{1}\}mbox{with}$ external resistor between \mbox{V}_{bb} and OUT



Terms

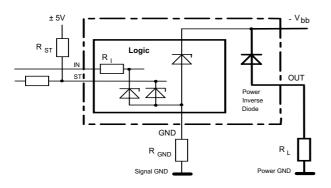


Input circuit (ESD protection)



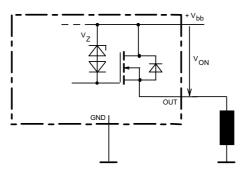
The use of ESD zener diodes as voltage clamp at DC conditions is not recommended

Reverse battery protection



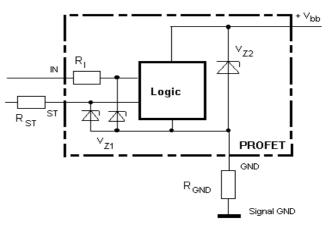
 R_{GND} =150 Ω , R_{I} =3.5k Ω typ., Temperature protection is not active during inverse current

Inductive and overvoltage output clamp



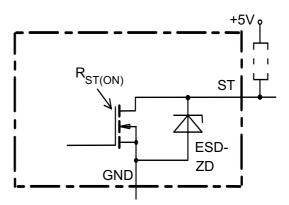
VON clamped to 59V min.

Overvoltage protection of logic part



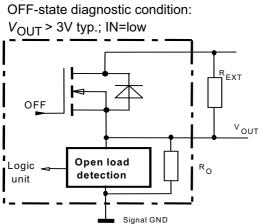
$$\begin{split} &V_{Z1}{=}6.1V \text{ typ., } V_{Z2}{=}V_{bb(AZ)}{=}62V \text{ min.,} \\ &R_{I}{=}3.5 \text{ k}\Omega \text{ typ., } R_{GND}{=}150\Omega \end{split}$$

Status output

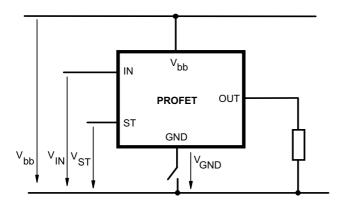




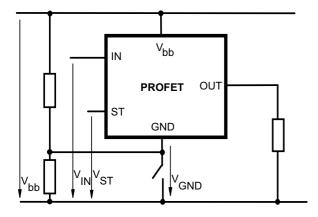
Open-load detection



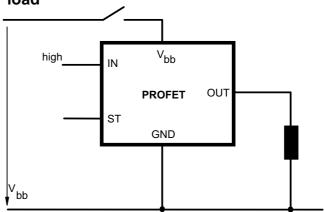
GND disconnect



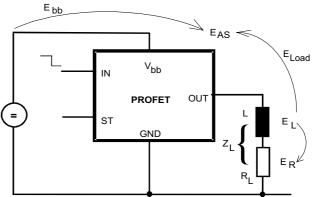
GND disconnect with GND pull up



$V_{\mbox{\scriptsize bb}}$ disconnect with charged inductive load



Inductive Load switch-off energy dissipation



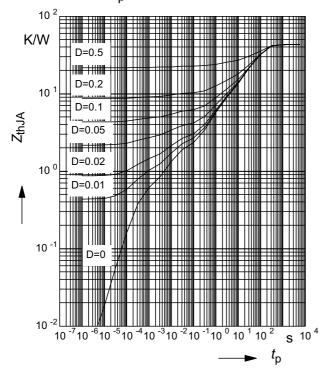
Energy stored in load inductance: $E_L = \frac{1}{2} * L * I_L^2$ While demagnetizing load inductance, the enérgy dissipated in PROFET is $E_{AS} = E_{bb} + E_L - E_R = V_{ON(CL)} * i_L(t) dt$, with an approximate solution for $R_L > 0\Omega$:

$$E_{AS} = \frac{I_L * L}{2 * R_L} * (V_{bb} + |V_{OUT(CL)|}) * \ln(1 + \frac{I_L * R_L}{|V_{OUT(CL)}|})$$

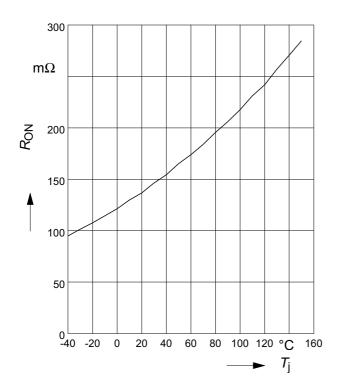


Typ. transient thermal impedance $Z_{\text{thJA}} = f(t_p) @ 6 \text{cm}^2$ heatsink area

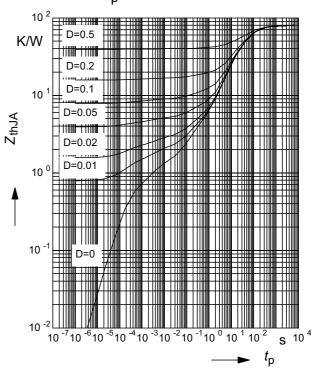
Parameter: $D=t_p/T$



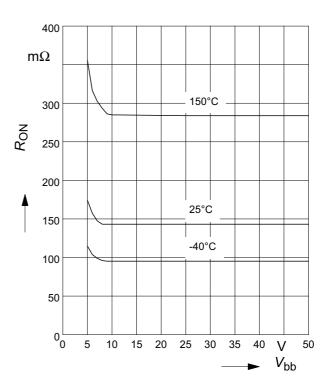
Typ. on-state resistance *R*_{ON} = f(*T*_j) ; *V*_{bb} = 13.5V ; *V*_{in} = high



Typ. transient thermal impedance $Z_{\text{thJA}}=f(t_p)$ @ min. footprint Parameter: $D=t_p/T$

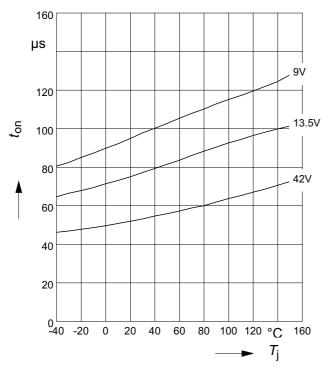


Typ. on-state resistance $R_{ON} = f(V_{bb}); I_L = 1 \text{ A}; V_{in} = \text{high}$

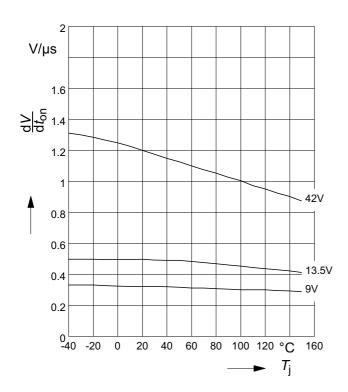




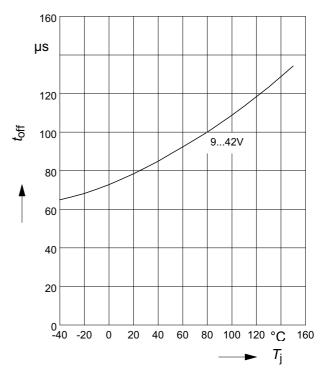
Typ. turn on time $t_{on} = f(T_j); R_L = 47\Omega$



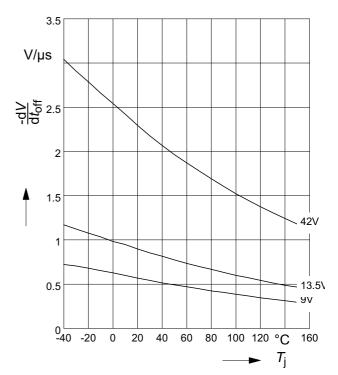
Typ. slew rate on $dV/dt_{on} = f(T_j)$; $R_L = 47 \Omega$



Typ. turn off time $t_{off} = f(T_i); R_L = 47\Omega$



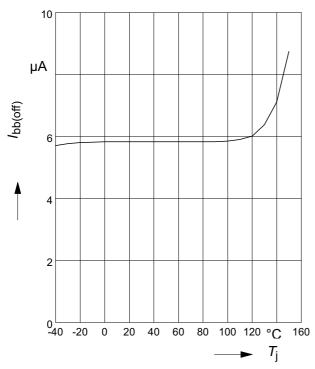
Typ. slew rate off $dV/dt_{off} = f(T_i); R_L = 47 \Omega$



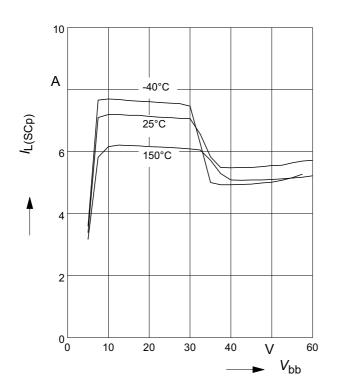


Typ. standby current

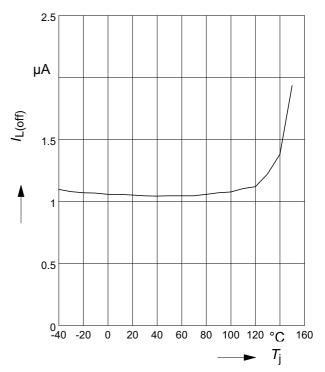
 $I_{bb(off)} = f(T_j)$; $V_{bb} = 42V$; $V_{IN} = Iow$



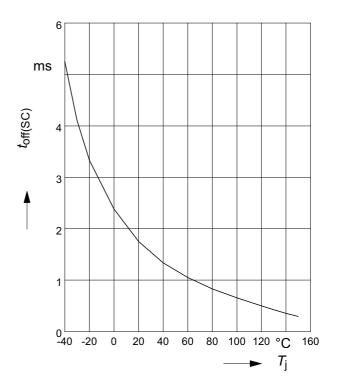
Typ. initial peak short circuit current limit $I_{L(SCp)} = f(V_{bb})$



Typ. leakage current $I_{L(off)} = f(T_j)$; $V_{bb} = 42V$; $V_{IN} = Iow$



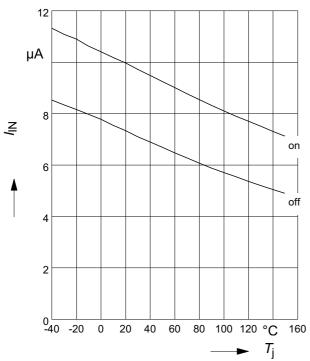
Typ. initial short circuit shutdown time $t_{off(SC)} = f(T_{j,start})$; $V_{bb} = 20V$

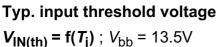


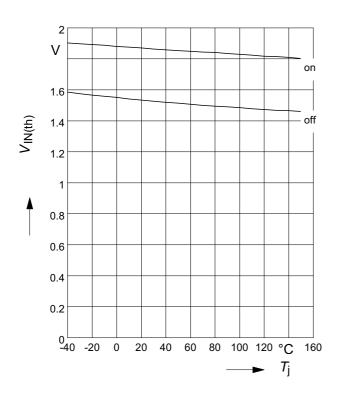


Typ. input current

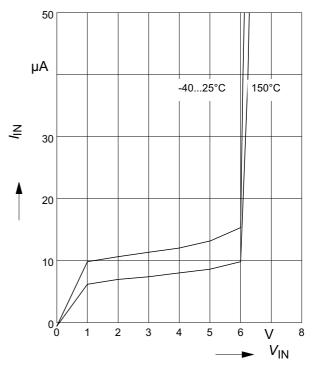
 $I_{IN(on/off)} = f(T_j); V_{bb} = 13.5V; V_{IN} = low/high$ $V_{INlow} \le 0.7V; V_{INhigh} = 5V$



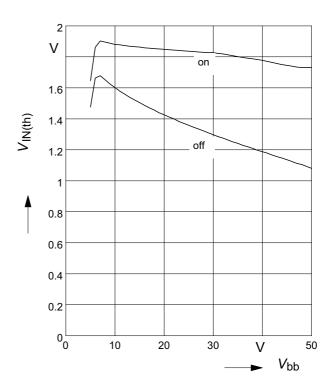




Typ. input current *I*_{IN} = f(*V*_{IN}); *V*_{bb} = 13.5V

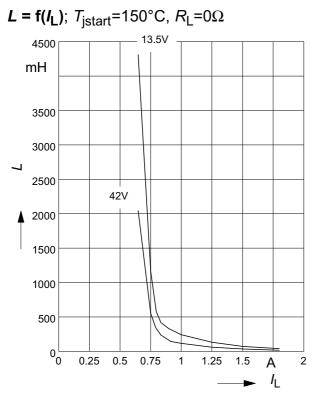


Typ. input threshold voltage $V_{IN(th)} = f(V_{bb})$; $T_j = 25^{\circ}C$

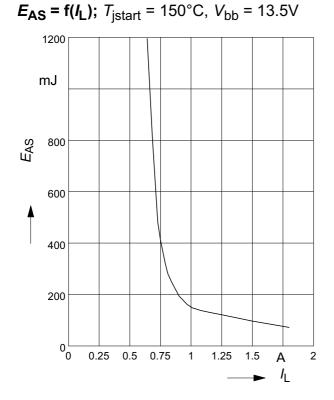




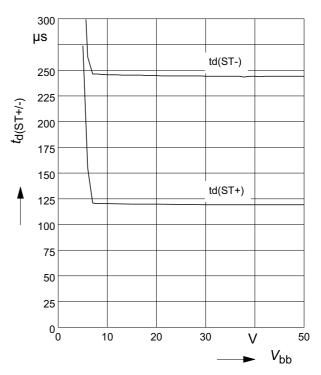
Maximum allowable load inductance for a single switch off



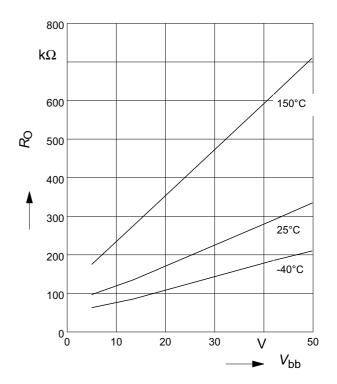
Maximum allowable inductive switch-off energy, single pulse



Typ. status delay time $t_{d(ST+/-)} = f(V_{bb}); T_j = 25^{\circ}C$

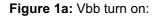


Typ. internal output pull down $R_{O} = f(V_{bb})$





Timing diagrams



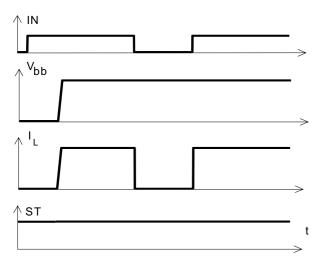


Figure 2b: Switching a lamp,

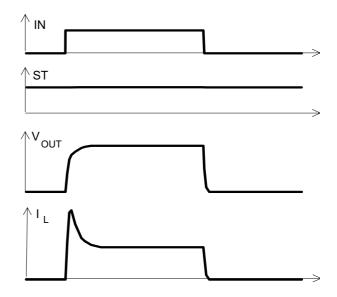


Figure 2a: Switching a resistive load, turn-on/off time and slew rate definition

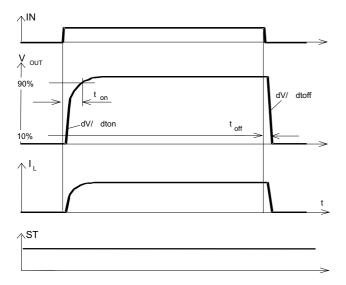


Figure 2c: Switching an inductive load

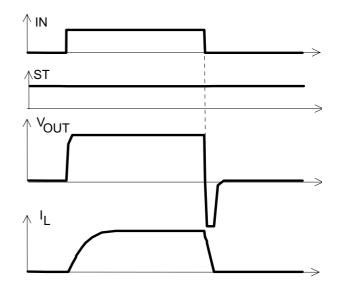
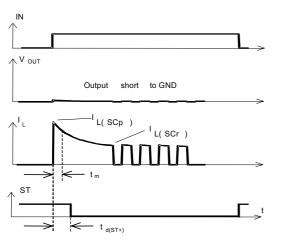
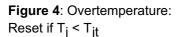




Figure 3a: Turn on into short circuit, shut down by overtemperature, restart by cooling



Heating up of the chip may require several milliseconds, depending on external conditions.



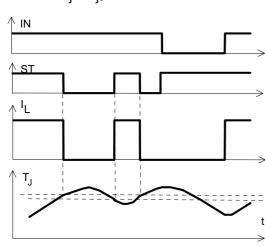
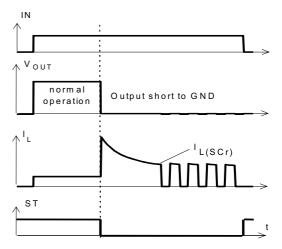
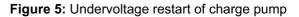


Figure 3b: Short circuit in on-state shut down by overtemperature, restart by cooling





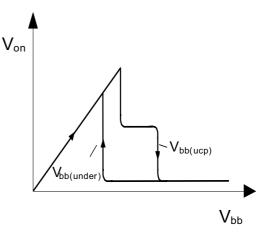
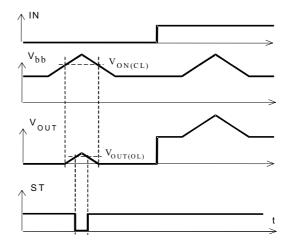


Figure 7: Overvoltage





Package Outlines

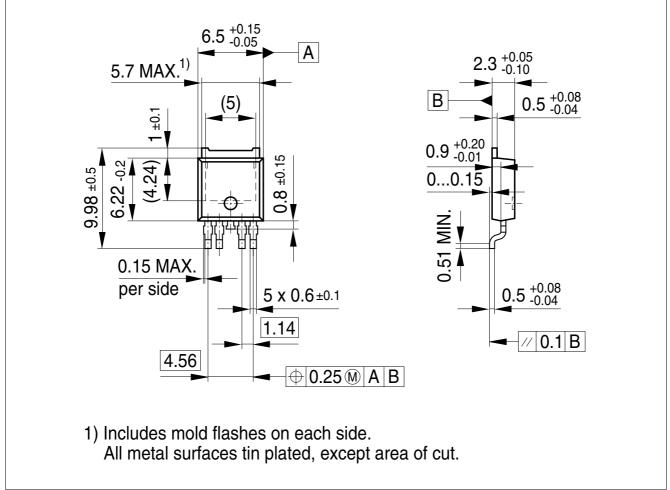


Figure 1 PG-TO252-5-11 (Plastic Dual Small Outline Package) (RoHS-compliant)

Green Product

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

Please specify the package needed (e.g. green package) when placing an order.



Revision History

Version	Date	Changes
V1.0	2004-01-27	initial version
V1.1	2007-01-15	AEC icon added
		RoHS icon added
		Green product (RoHS-compliant) added to the feature list
		Package information updated to green
		Green explanation added

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